

Abstract of the Disclosure:

In an electronic component having a piezo-electric resonator 10 formed on an element substrate 11 and obtaining a signal having a predetermined resonant frequency by a bulk wave propagating within a piezo-electric film 15, a mounting substrate 19 on which the piezo-electric resonator 10 is mounted
5 by face-down bonding through N bumps 18, when a maximum diameter of said N bumps 18 is defined as D μm , die shear strength of said N bumps 18 is not smaller than ND/6 (g), preferably, not smaller than ND/3.6 (g).